

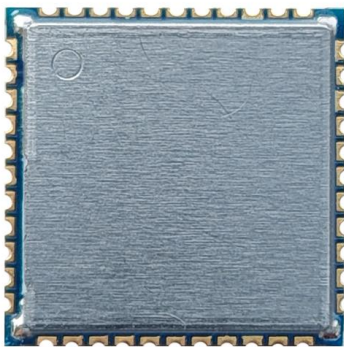


BL-M8800DS5-L

802.11ax 287Mbps WLAN + BLE v5.2

Combo SDIO/USB Module Specification

SHENZHEN BILIAN ELECTRONIC CO., LTD



(Top View)



(Bottom View)

Module Name: BL-M8800DS5-L	
Module Type: 802.11b/g/n/ax 287Mbps WLAN +BLE v5.2 Combo SDIO/USB Module	
Revision: V1.0	
Customer Approval:	
Company:	
Title:	
Signature:	Date:
Approval:	
Title:	
Signature:	Date:

Revision History

Revision	Summary	Release Date	Revised By
0.1	Initial release	2025-04-16	Cxf
1.0	Official release	2025-04-25	Cxf



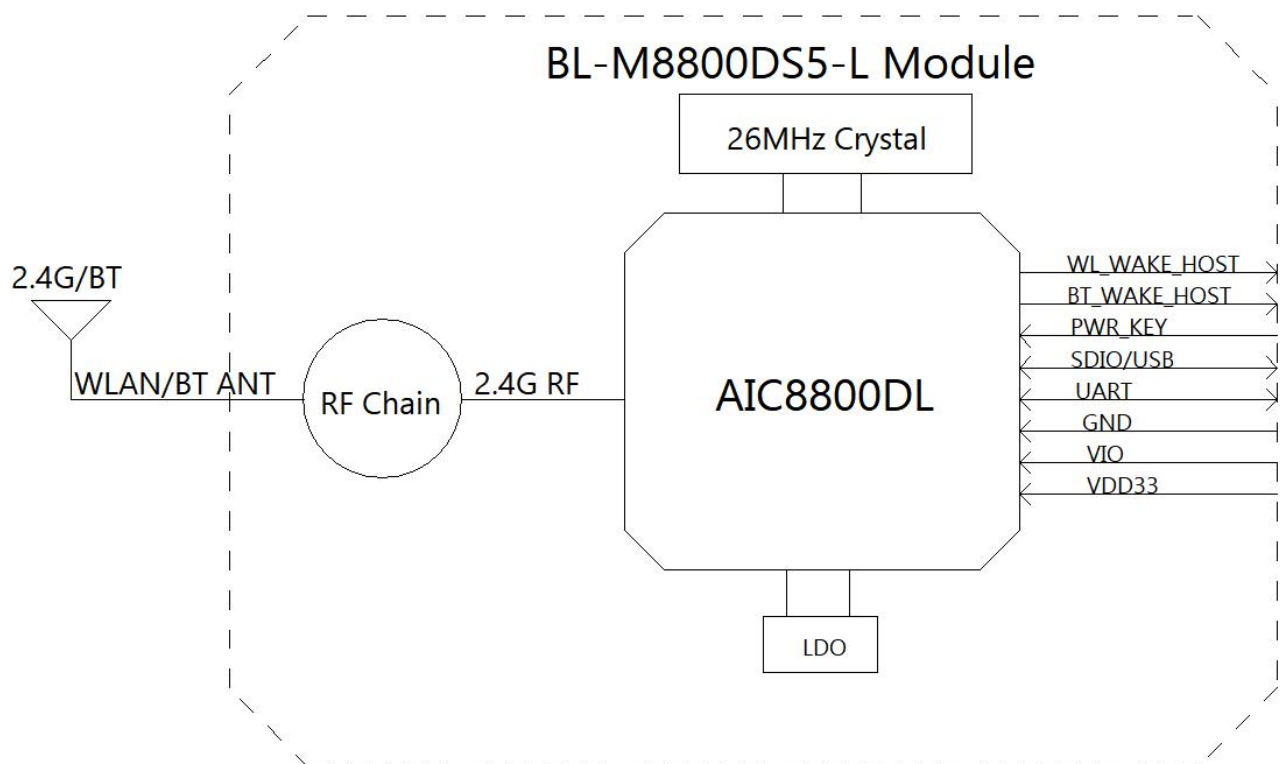
1. Introduction

BL-M8800DS5-L is a highly integrated WLAN + Bluetooth Combo module base on AIC8800DL chip, which combines a 1T1R WLAN subsystem and a BLE v5.2 subsystem. This module compatible IEEE 802.11b/g/n/ax standard and provides the maximum PHY rate up to 287Mbps, offering feature-rich wireless connectivity at high standards, delivering reliable, cost-effective and high throughput from an extended distance.

1.1 Features

- Operating Frequencies: 2.4~2.4835GHz
- Wireless PHY rate can reach up to 287Mbps with 20/40MHz bandwidth
- Host Interfaces are SDIO or USB 2.0 (Two interfaces cannot be used simultaneously)
- Support STA, AP, WLAN Direct modes concurrently
- Compatible Bluetooth core specification v5.2, supports BLE only

1.2 Block Diagram

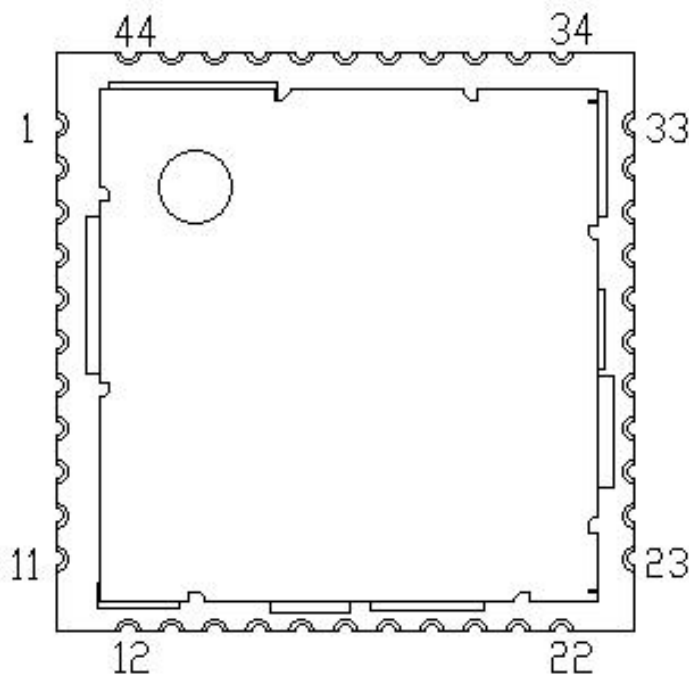




1.3 General Specifications

Module Name	BL-M8800DS5-L
Chipset	AIC8800DL
WLAN Standards	IEEE802.11b/g/n/ax
BT Specification	Bluetooth Core Specification v5.2
Host Interface	SDIO for WLAN & UART for Bluetooth or USB for WLAN + Bluetooth
Antenna	Connect to the external antenna through half hole pad
Dimension	12.0*12.0*2.05mm(L*W*H)
Power Supply	3.3V main power supply @600mA (Max) 3.3V or 1.8V I/O power supply
Operation Temperature	-20°C to +70°C
Operation Humidity	10% to 95% RH (Non-Condensing)

2. Pin Assignments



(Top view)

2.1 Pin Definition

No	Pin Name	Type	I/O Level	Module Pin Description
1	GND	RF	/	RF Ground connections

2	ANT0	RF	/	RF Pad for 2.4G WLAN/2.4G BT ANT
3	GND	RF	/	RF Ground connections
4	NC	/	/	NC
5	NC	/	/	NC
6	HOST_WAKE_BT	I/O	VIO	1.General Purpose Input / Output Pin GPIOB3 2.Host to wake-up this Bluetooth device input
7	BT_WAKE_HOST	I/O	VIO	1.General Purpose Input / Output Pin GPIOB2 2.Bluetooth device to wake-up Host output
8	NC	/	/	NC
9	VDD33	P	/	3.3V Main power supply
10	USB_DM	A I/O	/	USB 2.0 Device High Speed Interface differential pair
11	USB_DP	A I/O	/	USB 2.0 Device High Speed Interface differential pair
12	PWR_KEY	I	VDD33	Enable signal input, it can externally shut down the module by pulled low(Internal pull up to VDD33 by 47K and pull down to GND by 200K resistors)
13	WL_HOST_WAKE	I/O	VIO	1.General Purpose Input / Output Pin GPIOB1 2.WLAN device to wake-up host output
14	SD_D2	I/O	VIO	SDIO data line
15	SD_D3	I/O	VIO	SDIO data line
16	SD_CMD	I/O	VIO	SDIO command line
17	SD_CLK	I	VIO	SDIO clock line
18	SD_D0	I/O	VIO	SDIO data line
19	SD_D1	I/O	VIO	SDIO data line
20	GND	P	/	Ground connections
21	NC	/	/	NC
22	VIO	P	/	1.8V or 3.3V power supply for digital inputs/outputs, power-up timing requires VIO's power on time $\geq$ VDD33's. (USB application is recommended to use 3.3V I/O or 1.8V I/O; SDIO 3.0 application must use 1.8V I/O)
23	HOST_WAKE_WL	I/O	VIO	1.General Purpose Input / Output Pin GPIOB0 2. Host to wake-up this WLAN device input
24	NC	/	/	NC
25	PCM_DOUT	I/O	VIO	1. General Purpose Input / Output Pin GPIOA3 2. PCM serial data signal output
26	PCM_CLK	I/O	VIO	1.General Purpose Input / Output Pin GPIOA1 2. PCM clock signal
27	PCM_DIN	I/O	VIO	1. General Purpose Input / Output Pin GPIOA2 2. PCM serial data signal input
28	PCM_FSYNC	I/O	VIO	1.General Purpose Input / Output Pin GPIOA0 2. PCM frame sync signal
29	UART0_TX	O	VIO	High-Speed UART Data Out (Debug pin)
30	UART0_RX	I	VIO	High-Speed UART Data In (Debug pin)

31	GND	P	/	Ground connections
32	NC	/	/	NC
33	GND	P	/	Ground connections
34	NC	/	/	NC
35	NC	/	/	NC
36	GND	P	/	Ground connections
37	NC	/	/	NC
38	NC	/	/	NC
39	NC	/	/	NC
40	NC	/	/	NC
41	UART1_RTS	O	VIO	Bluetooth UART interface RTS
42	UART1_TX	O	VIO	Bluetooth UART interface TX
43	UART1_RX	I	VIO	Bluetooth UART interface RX
44	UART1_CTS	I	VIO	Bluetooth UART interface CTS

P: Power or Ground; I/O: In/Output; I: Input; O :Output; A I/O: Analog In/Output;
 AI: Analog Input; AO: Analog Output; RF: Analog RF Port or RF Ground

3. Electrical and Thermal Specifications

3.1 Recommended Operating Conditions

Parameters		Min	Typ	Max	Units
Ambient Operating Temperature		-20	25	70	°C
External Antenna VSWR			1.7	2.1	/
Supply Voltage	VDD33	3.1	3.3	3.5	V
	VIO_3.3V	3.1	3.3	3.5	V
	VIO_1.8V	1.7	1.8	1.9	V

3.2 DC Electrical Specification (Recommended Operation Conditions)

Symbol	Description	Min	Typ	Max	Units
VIL	CMOS Low Level Input Voltage	0	--	0.3*VIO	V
VIH	CMOS High Level Input Voltage	0.7*VIO	--	VIO	V
VTH	CMOS Threshold Voltage	--	0.5*VIO	--	V

3.3 Current Consumption

Conditions : SDIO for networking test under Linux, VDD33=3.3V, VIO=1.8V; UART for RF test under Windows, VDD33=3.3V, VIO=3.3V; Ta:25°C;

Use Case	VDD33 Current		
	Typ(I _{RMS})	Max(I _{Peak})	Units
WLAN & BT Unassociated (Linux SDIO Driver)	69	105	mA
2.4G WLAN throughput TX130Mbps (Linux SDIO Driver)	219	375	mA
2.4G WLAN throughput RX 134Mbps (Linux SDIO Driver)	168	377	mA
2.4G 11b 1Mbps TX@17dBm (TX RF test)	112	325	mA
2.4G 11g 6Mbps TX@17dBm (TX RF test)	151	412	mA
2.4G 11n HT20_MCS0 TX@16dBm (TX RF test)	152	411	mA
2.4G 11ax HE_SU 40M_MCS0 TX@16dBm (TX RF test)	117	415	mA
2.4G 11ax HE_SU 40M_MCS11 TX@13dBm (TX RF test)	88	386	mA
2.4G 11ax HE_SU 40M_MCS9 RX (RX RF test)	54	137	mA
BT LE_1M TX@6dBm (BT RF test, WLAN disable)	95	148	mA
BT LE_1M RX Active (BT RF test, WLAN disable)	45	129	mA

4. WLAN & Bluetooth RF Specifications

4.1 2.4G RF Specification

Conditions : VDD33=3.3V ; Ta:25°C

Features	Description
WLAN Standard	IEEE 802.11/b/g/n/ax
Frequency Range	2.4~2.4835GHz (2.4GHz ISM Band)
Channels	Ch1~Ch13 (For 20MHz Channels)
Modulation	802.11b (DSSS): DBPSK, DQPSK, CCK; 802.11g (OFDM): BPSK, QPSK, 16QAM, 64QAM; 802.11n (OFDM): BPSK, QPSK, 16QAM, 64QAM; 802.11ax (OFDMA): BPSK, BPSK_DCM, QPSK, QPSK_DCM, QAM16, QAM16_DCM, QAM64, QAM256, QAM1024;
Data Rate	802.11b: 1, 2, 5.5, 11Mbps; 802.11g: 6, 9, 12, 18, 24, 36, 48, 54Mbps; 802.11n (HT20): MCS0~MCS7(1T1R_SISO) 6.5~72.2Mbps; 802.11n (HT40): MCS0~MCS7(1T1R_SISO) 13.5~150Mbps; 802.11ax (HE_MU,OFDMA 26~242RU): MCS0~MCS11(1T1R) 0.4~143.4Mbps; 802.11ax (HE_SU, non-OFDMA 20MHz): MCS0~MCS11(1T1R) 3.6~143.4Mbps;

	802.11ax (HE_SU, non-OFDMA 40MHz): MCS0~MCS11(1T1R) 7.3~286.8Mbps;		
Frequency Tolerance	≤ ±20ppm		
2.4G Transmitter Specifications (TX power tolerance calibrated, customers can define the target TX power within recommended range by modifying configuration file of the driver software, Customers must define the TX power same or lower than recommended Target TX Power as below.) for EU			
TX Rate	Recommended Target TX Power For EU (dBm)	TX Power Tolerance (dBm)	EVM (dB)
802.11b@1Mbps	17	±2	≤ -10
802.11b@11Mbps	17	±2	≤ -10
802.11g@6Mbps	17	±2	≤ -10
802.11g@54Mbps	14	±2	≤ -25
802.11n@HT20_MCS0	16	±2	≤ -10
802.11n@HT20_MCS7	14	±2	≤ -28
802.11n@HT40_MCS0	16	±2	≤ -10
802.11n@HT40_MCS7	14	±2	≤ -28
802.11ax@HE_SU 40M_MCS0	16	±2	≤ -15
802.11ax@HE_SU 40M_MCS11	13	±2	≤ -35
2.4G Receiver Specifications			
RX Rate	Min Input Level (Typ. dBm)	Max Input Level (Typ. dBm)	PER
802.11b@1Mbps	-93	-5	< 8%
802.11b@11Mbps	-87	-5	< 8%
802.11g@6Mbps	-92	-5	< 10%
802.11g@54Mbps	-75	-5	< 10%
802.11n@HT20_MCS0	-91	-5	< 10%
802.11n@HT20_MCS7	-73	-5	< 10%
802.11n@HT40_MCS0	-88	-5	< 10%
802.11n@HT40_MCS7	-70	-5	< 10%
802.11ax@HE_SU 40M_MCS0	-87	-5	< 10%
802.11ax@HE_SU 40M_MCS9	-64	-5	< 10%

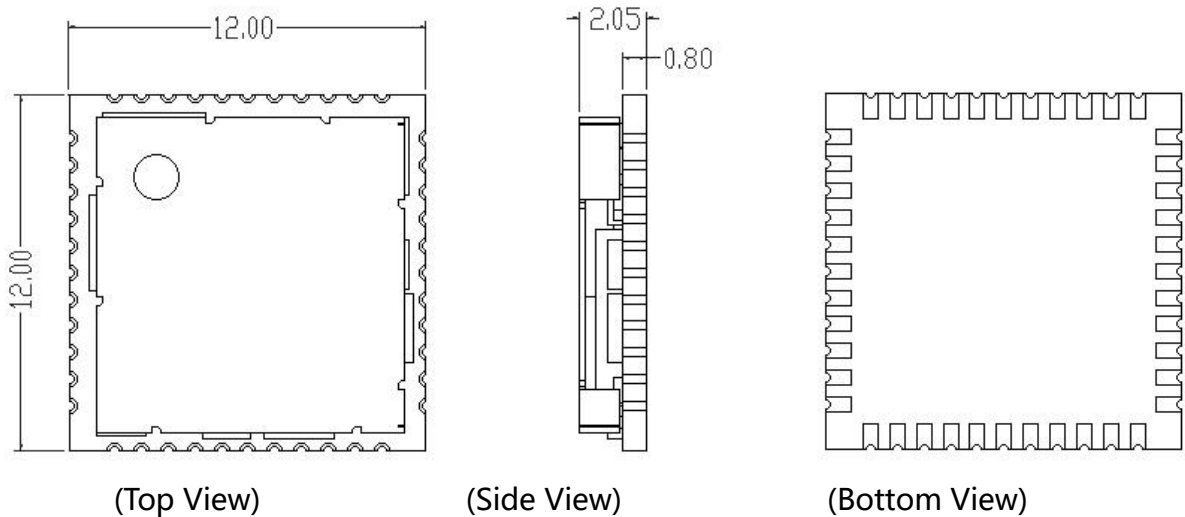
4.3 Bluetooth RF Specification

Conditions: VDD33 =3.3V; Ta:25°C	
Features	Description
Bluetooth Specification	Bluetooth Core Specification v5.2/v4.2/v4.0
Frequency Range	2.4~2.4835GHz(2.4GHz ISM Band)

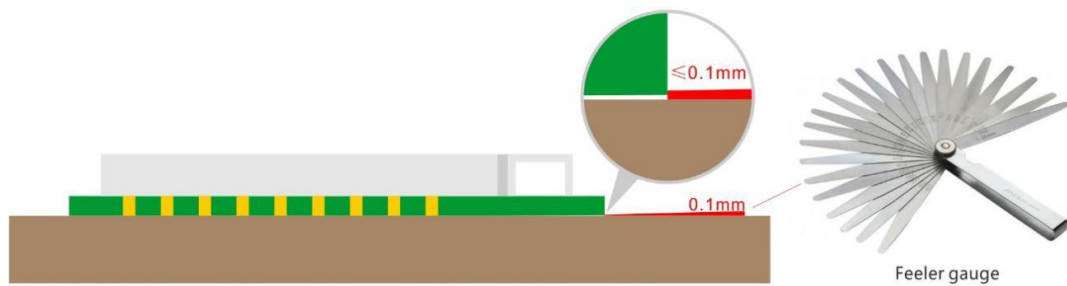
Channels	Blue Low Energy: Ch0~Ch39 (For 2MHz Channels);			
Power Classes	Bluetooth Low Energy: Class1.5;			
Data Rate & Modulation	LE_125Kbps: GFSK (Coded_S=8); LE_500Kbps: GFSK (Coded_S=2); LE_1Mbps: GFSK (Uncoded); LE_2Mbps: GFSK (Uncoded);			
Bluetooth Transmitter Specifications for EU				
Items	Min (dBm)	Typ (dBm)	Max (dBm)	
TX Power				
LE_125/500K	2	6	10	
LE_1M	2	6	10	
LE_2M	2	6	10	
LE_1M Modulation Characteristics				
Δf1avg	225KHz	252.3KHz	275KHz	
Δf2avg	185KHz	216.56KHz	275KHz	
Δf2max	185KHz	220.1.4KHz	/	
Δf2avg/Δf1avg	0.8	0.86	/	
LE_2M Modulation Characteristics				
Δf1avg	450KHz	499.25KHz	550KHz	
Δf2avg	370KHz	469.13KHz	550KHz	
Δf2max	370KHz	439.38KHz	/	
Δf2avg/Δf1avg	0.8	0.94	/	
Bluetooth Receiver Specifications				
Items	Sensitivity		Maximum Input Level	
	Input Level(Typ. dBm)	PER	Input Level (Typ. dBm)	PER
LE_125/500K	-94	≤ 5%	-5	≤ 5%
LE_1M	-92	≤ 5%	-5	≤ 5%
LE_2M	-91	≤ 5%	-5	≤ 5%

5. Mechanical Specifications

5.1 Module Outline Drawing (units:mm)

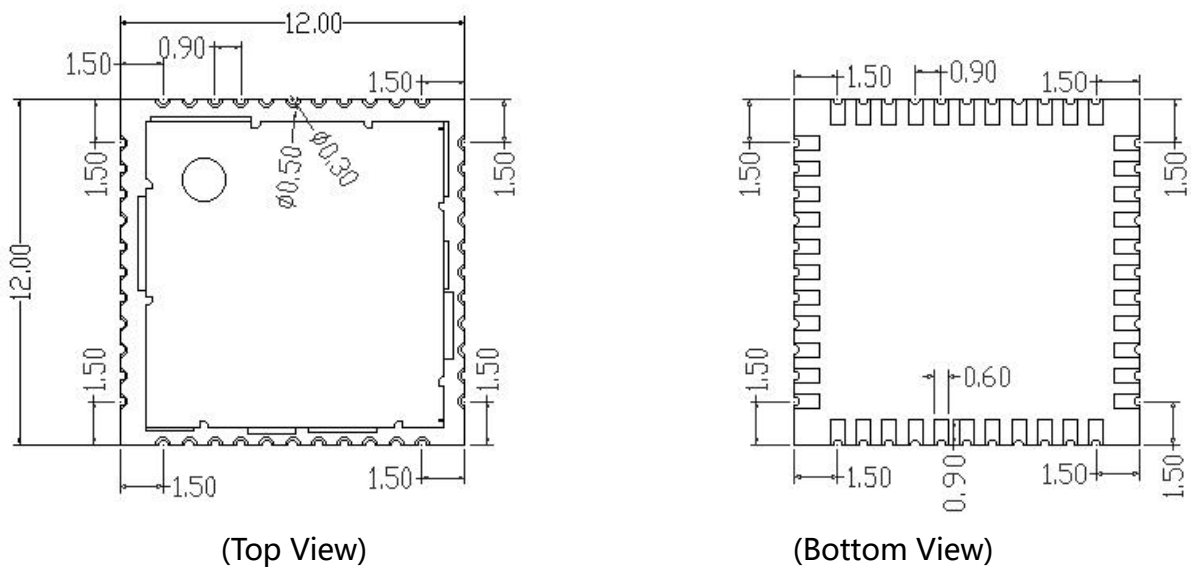


Module dimension: 12.0*12.0*2.05mm (L*W*H; Tolerance: $\pm 0.3\text{mm}_L/W$, $\pm 0.2\text{mm}_H$)



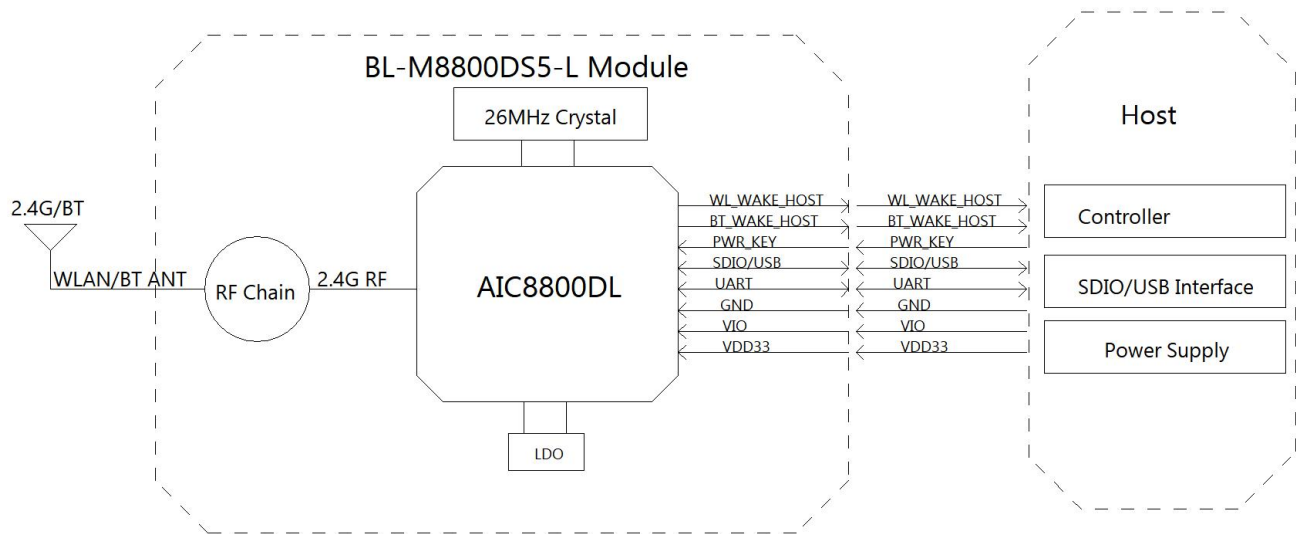
Module Bow and Twist: $\leq 0.1\text{mm}$

5.2 Mechanical Dimensions (units:mm)



6. Application Information

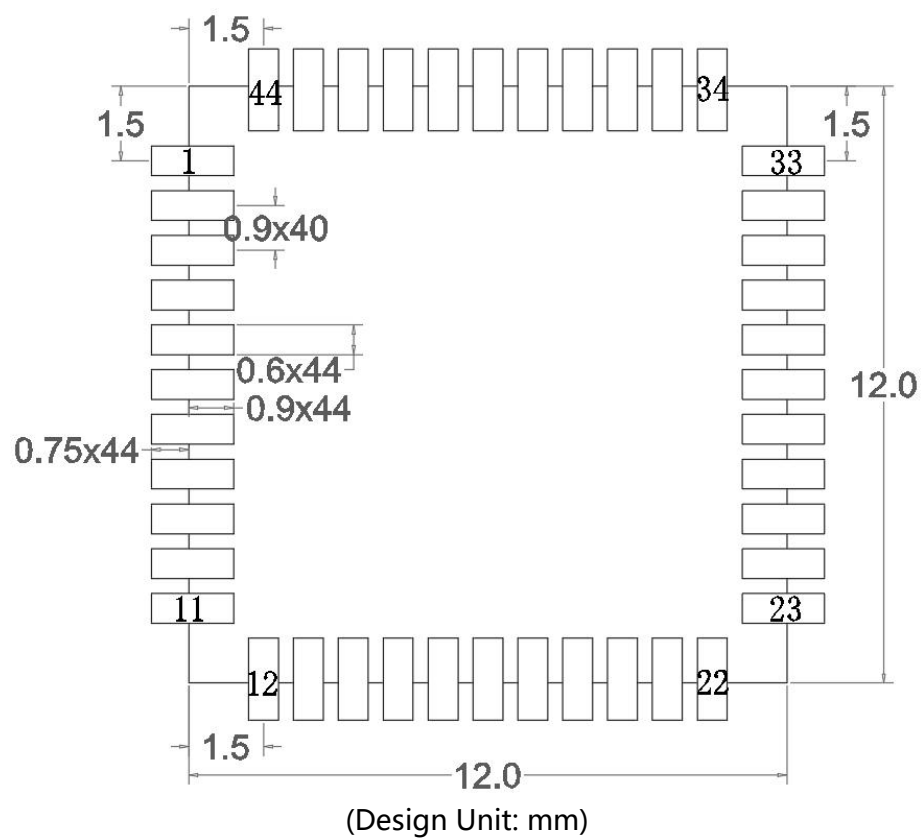
6.1 Typical Application Circuit



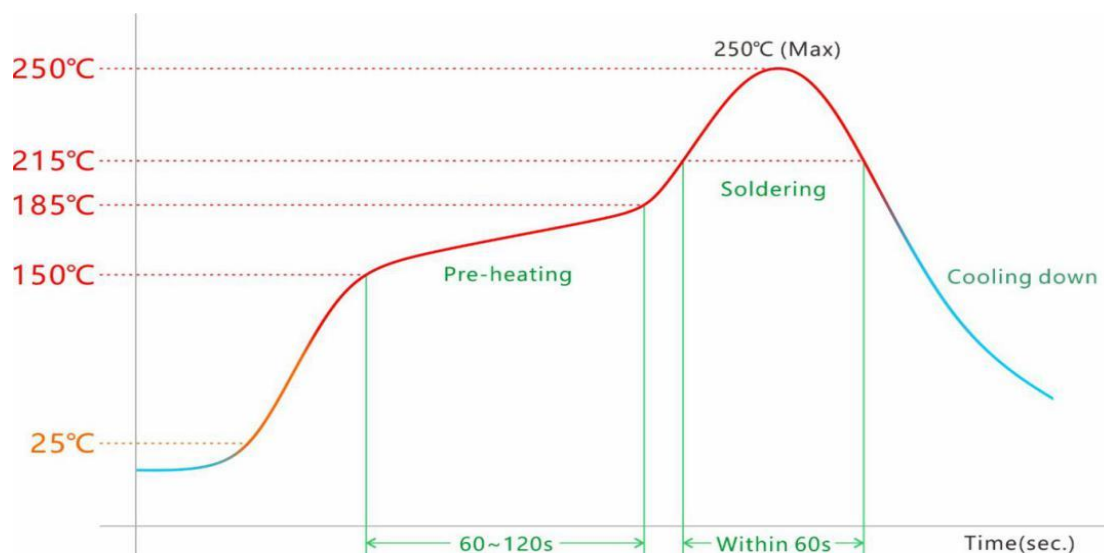
6.2 HW Application Note

- RF path needs to maintain 50 ohm impedance.
- The module UART_TX is connected to the RX of the master circuit, and the UART_RX is connected to the TX of the master circuit.
- Keep the SDIO lines as equal as possible and minimize the distance between the host and the module. **Make sure SD_CLK has a good ground reference.**
- Main power supply voltage: DC 3.1 ~ 3.5V, ripple voltage <80mV
- Maximum RMS current $\geq 400\text{mA}$ and maximum peak current $\geq 600\text{mA}$
- For fast transient response, a current mode buck converter is recommended.
- The USB high speed differential pair should be maintain $90\Omega \pm 5\Omega$ differential impedance.
- USB signal pairs as short as possible, avoid interference from Power and other signals.

6.3 Recommend PCB Layout Footprint(units:mm)



6.4 Reflow Soldering Standard Conditions



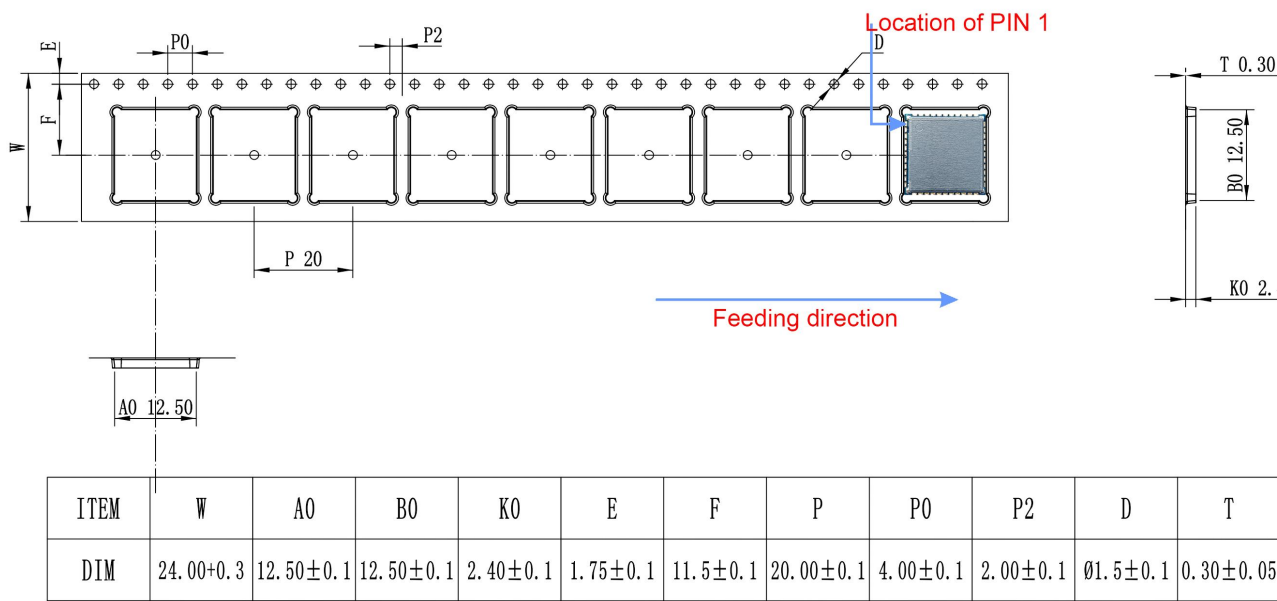
Please use the reflow within 2 times.
Set up the highest temperature within 250°C.

7. Key Components Of Module

No.	Parts	Specification	Manufacturer	Note
1	Chipset	AIC8800DL	AIC Semiconductor (Shanghai) CO.,LTD	
2	PCB	BL-M8800DS5	SHEN ZHEN QILI ELECTRON CO.,LTD	
			Quzhou Sunlord Electronics Co.,Ltd	
			ShenZhen Tie Fa Technology Limited	
3	Crystal	26MHz-3225	LUCKI CM ELECTRONICS CO.,LTD	
			Chengde oscillator Electronic Technology CO.,LTD	
			JinHua East Crystal Electronic CO.,LTD	
			HUBEI TKD CRYSTAL ELECTRONIC SCIENCE AND TECHNOLOGY CO.,LTD	

8. Package and Storage Information

8.1 Package Dimensions





Package specification:

1. 1,000 modules per roll and 5,000 modules per box.
2. Outer box size: 37.5*36*29cm.
3. The diameter of the blue environment-friendly rubber plate is 13 inches, with a total thickness of 28mm (with a width of 24mm carrying belt).
4. Put 1 package of dry agent (20g) and humidity card in each anti-static vacuum bag.
5. Each carton is packed with 5 boxes.

8.2 Storage Conditions

Absolute Maximum Ratings:

Storage temperature: -40°C to +85°C

Storage humidity: 10% to 95% RH (Non-Condensing)

Recommended Storage Conditions:

Storage temperature: 5°C to +40°C

Storage humidity: 20% to 90% RH

Please use this Module within 12month after vacuum-packaged.

The Module shall be stored without opening the packing.

After the packing opened, the Module shall be used within 72hours.

When the color of the humidity indicator in the packing changed, the Module shall be baked before soldering.

Baking condition: 60°C, 24hours, 1time.

ESD Sensitivity:

ESD Protection: 2KV(HBM, Maximum rating)

The Module is a static-sensitive electronic device.

Do not operate or store near strong electrostatic fields.

Take proper ESD precautions!



ESD CAUTION

2.1 FCC Certification

Integration instructions for host product manufacturers according to KDB 996369 D03 OEM Manual v01r01

2.2 List of applicable FCC rules

The BL-M8800DS5-L is a 802.11b/g/n/ax 287Mbps WLAN +BLE v5.2 Combo SDIO/USB Module . It is within U.S. FCC part 15.247 standard

2.3 Specific operational use conditions

The EUT is a 802.11b/g/n/ax 287Mbps WLAN +BLE v5.2 Combo SDIO/USB Module
Operation Frequency: 2402-2480MHz for BLE; 2412-2462MHz for WIFI 2.4G,
Modulation GFSK for BLE,WLAN(DSSS/OFDM/OFDMA)

2.4 Limited module procedures

Not applicable; Single Modular Approval Request

2.5 Trace antenna designs

The BL-M8800DS5-L is a 802.11b/g/n/ax 287Mbps WLAN +BLE v5.2 Combo SDIO/USB Module beams signals and communicates with its antenna, which is FPC Antenna.

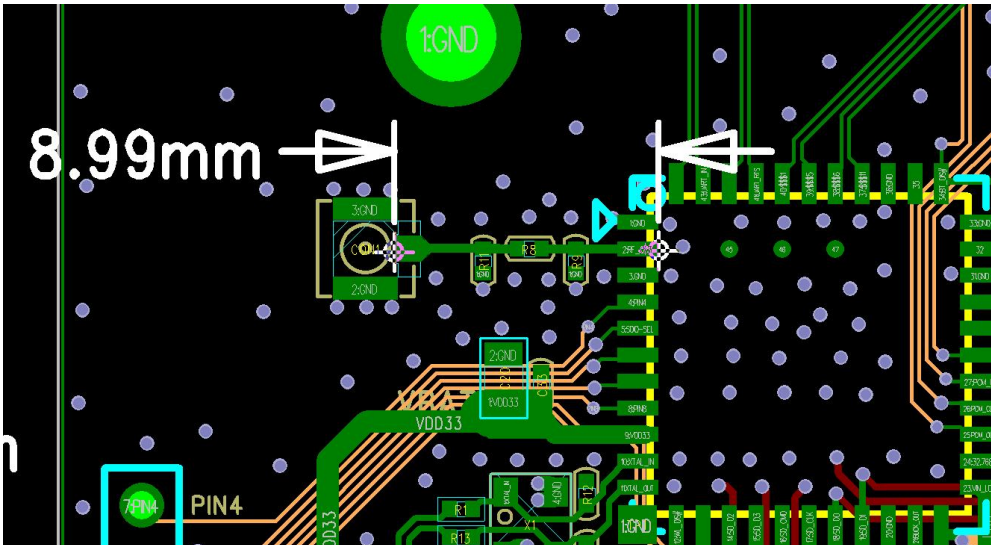
Users should connect antennas to half hole pad through FP types of RF trace and the trace impedance must be controlled in 50Ω. recommends that the total insertion loss between the antenna pads and antennas should meet the following requirements:

Trace loss

Frequency	Loss
2400MHz-2500MHz	<0.6dB

To facilitate the antenna tuning and certification test, a RF connector and an antenna matching circuit should be added. The following figure is the recommended circuit.

From CON1 port to PCB module, the R8: 0Ω, R9: NC(Normally Closed) R11: NC(Normally Closed)



The module needs to be attached to the PCB board and connected to the external antenna through the solder joint of the circuit on the PCB. the internal structure is FPC. A resistance of 0R is added between the module and the antenna at L1 to ensure that the impedance of the connection between the module and the antenna reaches 50R.The ANT1 position on the PCB is where the external antenna is connected.

2.6 RF exposure considerations

To maintain compliance with FCC's RF Exposure guidelines, This equipment should be installed and operated with minimum distance between 20cm the radiator your body: Use only the supplied antenna.

2.7 Antennas

BL-M8800DS5-L is a 802.11b/g/n/ax 287Mbps WLAN +BLE v5.2 Combo SDIO/USB Module beams signals and communicates with its antenna, which have four FPC Antenna

The antenna pads and antennas should meet the following requirements:

1	115C	FPC antenna	3.98dBi
2	A10	FPC antenna	2.96dBi
3	Q10	FPC antenna	3.37dBi
4	450L	FPC antenna	0.50dBi

2.8 Label and compliance information

The final end product must be label in a visible area , the Host must Contains FCC ID: 2AL6KBL-M8800DS5-L.

2.9 Information on test modes and additional testing requirements

Data transfer module demo board can control the EUT work in RF test mode at specified test channel.

2.10 Additional testing, Part 15 Subpart B disclaimer

The module without unintentional-radiator digital circuit, so the module does not required an evaluation by FCC Part 15 Subpart B. The host should be evaluated by the FCC Subpart B

2.11 OEM integration instructions:

This device is intended only for OEM integrators under the following conditions: The transmitter module may not be co-located with any other transmitter or antenna. The module shall be only used with the external antenna(s) that has been originally tested and certified with this module. As long as the conditions above are met, further transmitter test will not be required. However, the OEM integrator is still responsible for testing their end-product for any additional compliance requirements required with this module installed (for example, digital device emissions, PC peripheral requirements, etc.).

2.12 Validity of using the module certification:

In the event that these conditions cannot be met (for example certain laptop configurations or co-location with another transmitter), then the FCC authorization for this module in combination with the host equipment is no longer considered valid and the FCC ID of the module cannot be used on the final product. In these circumstances, the OEM integrator will be responsible for re-evaluating the end product (including the transmitter) and obtaining a separate FCC authorization.

ATTENTION

This device is intended only for OEM integrators under the following conditions:

- 1) The antenna must be installed such that 5 mm is maintained between the antenna and users, and
- 2) This device and its antenna(s) must not be co-located with any other transmitters except in accordance with FCC multi-transmitter product procedures. Referring to the multi-transmitter policy, multiple transmitter(s) and module(s) can be operated simultaneously without C2PC.
- 3) For all products market in US, OEM has to limit the Operating Frequency: 2402-2480MHz for BT; 2412-2462MHz for WIFI 2.4G by supplied firmware programming tool. OEM shall not supply any tool or info to the end-user regarding to Regulatory Domain change.

USERS MANUAL OF THE END PRODUCT:

In the user manual of the end product, the end user has to be informed to keep at least 5mm separation with the antenna while this end product is installed and operated. The end user has to be informed that the FCC radio-frequency exposure guidelines for an uncontrolled environment can be satisfied. The end user has to also be informed that any changes or modifications not expressly approved by the manufacturer could void the user's authority to operate this equipment.

FCC Caution:

This device complies with part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

Any Changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.

This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

transmitter.

ISED Statement

- English: This device complies with Innovation, Science and Economic Development Canada's licence - exempt RSS standard(s). Operation is subject to the following two conditions: (1) This device may not cause interference, and (2) This device must accept any interference, including interference that may cause undesired operation of the device. The digital apparatus complies with Canadian CAN ICES - 3 (B)/NMB - 3(B).

- French: L'émetteur/récepteur exempt de licence contenu dans le présent appareil est conforme aux CNR d'Innovation, Sciences et Développement économique Canada applicables aux appareils radio exempts de licence. L'exploitation est autorisée aux deux conditions suivantes : (1) l'appareil ne doit pas produire de brouillage, et (2) l'utilisateur de l'appareil doit accepter tout brouillage radioélectrique subi, même si le brouillage est susceptible d'en compromettre le fonctionnement.

This radio transmitter (ISED certification number: 20944-BLM8800DS5L) has been approved by Industry Canada to operate with the antenna types listed with the maximum permissible gain indicated. Antenna types not included in this list, having a gain greater than the maximum gain indicated for that type, are strictly prohibited for use with this device.

Le présent émetteur radio (ISED certification number: 20944-BLM8800DS5L) a été approuvé par Industrie Canada pour fonctionner avec les types d'antenne énumérés ci-dessous et ayant un gain admissible maximal. Les types d'antenne non inclus dans cette liste, et dont le gain est supérieur au gain maximal indiqué, sont strictement interdits pour l'exploitation de l'émetteur.

Operation Frequency: 2402-2480MHz for BT; 2412-2462MHz for WIFI 2.4G,
Modulation GFSK for BLE, WLAN (DSSS/OFDM/OFDMA)

This equipment complies with FCC/IC RSS-102 radiation exposure limits set forth for an uncontrolled environment. This equipment should be installed and operated with minimum distance 20cm between the radiator & your body.

Ce matériel est conforme aux limites de dose d'exposition aux rayonnements, telles qu'énoncées dans un autre environnement. Ce matériel devrait être installé et exploité avec une distance minimale de 20 cm entre le radiateur et votre corps.



Radiation Exposure Statement

This equipment complies with Canada radiation exposure limits set forth for an uncontrolled environment. This equipment should be installed and operated with minimum distance 20cm between the radiator & your body.

Déclaration d'exposition aux radiations

Cet équipement est conforme Canada limites d'exposition aux radiations dans un environnement non contrôlé. Cet équipement doit être installé et utilisé à distance minimum de 20cm entre le radiateur et votre corps.

This device is intended only for OEM integrators under the following condition:

The transmitter module may not be co-located with any other transmitter or antenna.

As long as the condition above is met, further transmitter test will not be required. However, the OEM integrator is still responsible for testing their end-product for any additional compliance requirements required with this module installed.

Cet appareil est destiné uniquement aux intégrateurs OEM dans les conditions suivantes : Le module émetteur ne peut pas être placé à côté d'un autre émetteur ou d'une autre antenne.

Tant que la condition ci-dessus est remplie, aucun test supplémentaire de l'émetteur ne sera nécessaire. Cependant, l'intégrateur OEM est toujours responsable de tester son produit final pour toute exigence de conformité supplémentaire requise avec ce module installé.

**Important Note:**

In the event that these conditions cannot be met (for example certain laptop configurations or co-location with another transmitter), then the Canada authorization is no longer considered valid and the IC cannot be used on the final product. In these circumstances, the OEM integrator will be responsible for re-evaluating the end product (including the transmitter) and obtaining a separate Canada authorization.

Note Importante:

Dans le cas où ces conditions ne peuvent être satisfaites (par exemple pour certaines configurations d'ordinateur portable ou de certaines co-localisation avec un autre émetteur), l'autorisation du Canada n'est plus considéré comme valide et l'IC ne peut pas être utilisé sur le produit final. Dans ces circonstances, l'intégrateur OEM sera chargé de réévaluer le produit final (y compris l'émetteur) et l'obtention d'une autorisation distincte au Canada.

End Product Labeling

The final end product must be labeled in a visible area with the following: Contains IC: 20944-BLM8800DS5L.

Plaque signalétique du produit final

Le produit final doit être étiqueté dans un endroit visible avec l'inscription suivante: Contient des IC: 20944-BLM8800DS5L.

Manual Information to the End User

The OEM integrator has to be aware not to provide information to the end user regarding how to install or remove this RF module in the user's manual of the end product which integrates this module.

The end user manual shall include all required regulatory information/warning as show in this manual.

Manuel d'information à l'utilisateur final

L'intégrateur OEM doit être conscient de ne pas fournir des informations à l'utilisateur final quant à la façon d'installer ou de supprimer ce module RF dans le manuel de l'utilisateur du produit final qui intègre ce module.

Le manuel de l'utilisateur final doit inclure toutes les informations réglementaires requises et avertissements comme indiqué dans ce manuel.

